HClamp2481ZA

EMIClamp ®

24V ESD, Surge, & EMI Protection

Description

HClamp® TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. These state-of-the-art devices utilize solid-state silicon-avalanche technology for superior clamping performance and DC electrical characteristics.

HClamp2481ZA is in a DFN 0.60 x 0.30 x 0.25mm 2-Lead package. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. HClamp2481ZA also provides high surge current capability (4.5A, tp=8/20µs). They have been optimized for ESD protection of data and power lines in cellular phones and other portable electronics.

Features

- Transient protection for VBus and data lines to
  - IEC 61000-4-2 (ESD): ±30kV (Contact), ±30kV (Air)
  - IEC 61000-4-5 (Lightning): 4.5A (tp = 8/20µs)
- Ultra-small package
- Protects one power or data line
- Low ESD clamping voltage
- Working voltage: 24V
- Capacitance: 5.5pF (maximum)
- Low leakage current
- Low dynamic resistance: 0.4Ω (typ)
- Solid-state silicon-avalanche technology

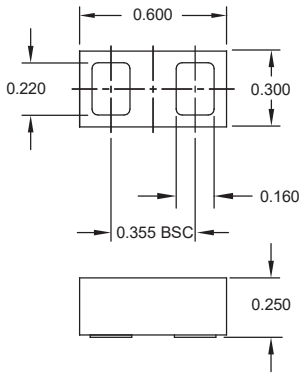
Applications

- Cellular Handsets & Accessories
- Wearables
- Industrial Equipment
- Portable electronics

Mechanical Characteristics

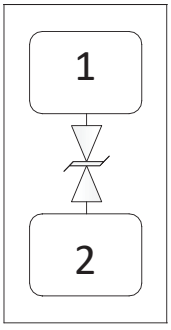
- Package: DFN 0.60 x 0.30 x 0.25mm 2-Lead
- Pb-Free, Halogen Free, RoHS/WEEE compliant
- Lead Finish: Pb-Free
- Marking: Marking code
- Packaging: Tape and Reel

Package Dimension



Nominal Dimensions in mm

Schematic and Pin Configuration



DFN 0.60 x 0.30 x 0.25mm-2 Lead (Bottom View)

Absolute Maximum Rating

RATING	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20µs)	P_{PK}	195	W
Peak Pulse Current (tp = 8/20µs)	I_{PP}	4.5	A
ESD per IEC 61000-4-2 (Contact)(1)	V_{ESD}	±30	kV
ESD per IEC 61000-4-2 (Air)(1)		±30	
Operating Temperature	T_J	-40 to +85	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics

T=25°C unless otherwise specified

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse Stand-Off Voltage	V_{RWM}				24	V
Reverse Breakdown Voltage	V_{BR}	I_t = 1mA	25	26.6	29	V
Reverse Leakage Current	I_R	V_{RWM} = 24V		<1	100	nA
Trigger Voltage(2)	V_{tr}	I_{tr} = 1A, t_p = 0.2/100ns			30	V
Clamping Voltage(3)	V_C	I_{PP} = 4.5A, t_p = 1.2/50µs (Voltage), 8/20µs (Current) Combination Waveform, R_S = 2 Ω		35.8	43.3	V
ESD Clamping Voltage(4)	V_C	I_{TLP}=4A, t_p=0.2/100ns (TLP)		26		V
		I_{TLP}=16A, t_p=0.2/100ns (TLP)		31.1		
Dynamic Resistance(4),(5)	R_{DYN}	t_p = 0.2/100ns		0.4		Ω
Junction Capacitance	C_J	V_R = 0V, f = 1MHz		4.4	5.5	pF

Notes:

1) ESD gun return path connected to ESD ground plane.

2) Guaranteed by design, not production tested.

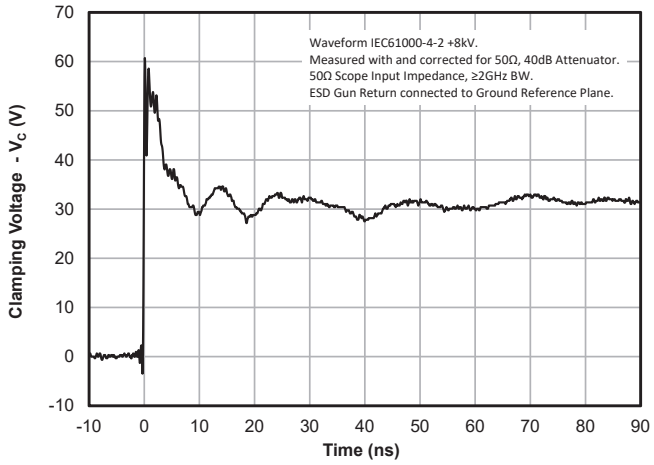
3) Measured using a 1.2/50µs voltage, 8/20µs current combination waveform, R_S = 2 Ohms. Clamping is defined as the clamping voltage after the device snaps back to a conducting state.

4) Transmission Line Pulse Test (TLP) Settings: t_p = 100ns, t_r = 0.2ns, I_{TLP} and V_{TLP} averaging window: t_1 = 70ns to t_2 = 90ns.

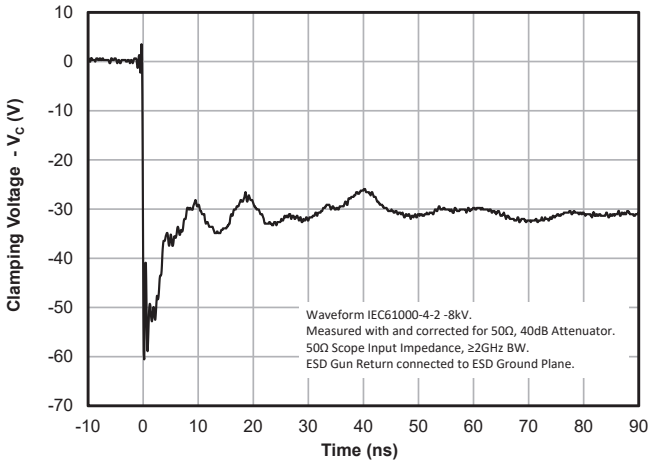
5) Dynamic resistance calculated from I_{TLP} = 4A to I_{TLP} = 16A

Typical Characteristics

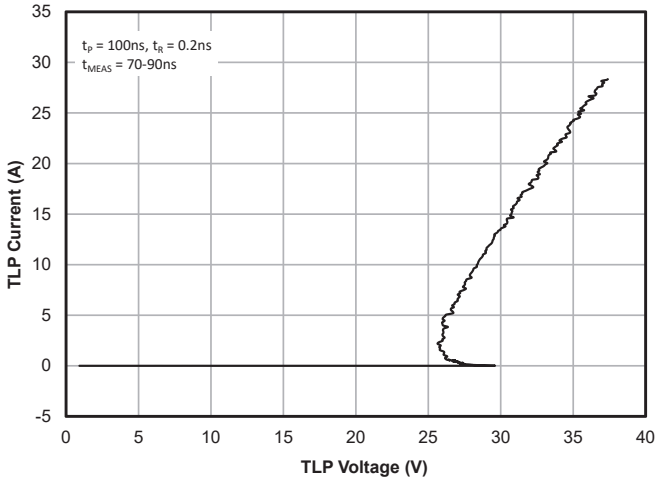
ESD Clamping (8kV Contact per IEC 61000-4-2)



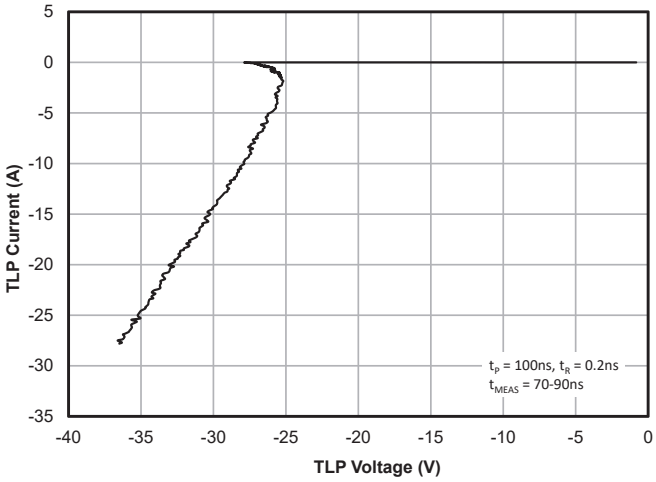
ESD Clamping (-8kV Contact per IEC 61000-4-2)



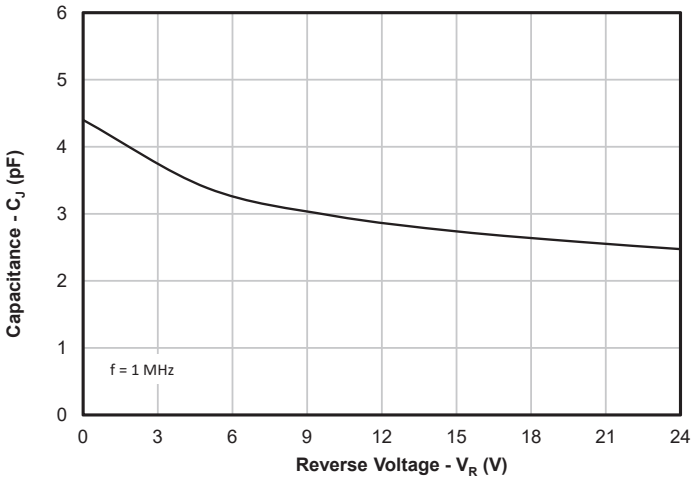
TLP Characteristic (Positive Pulse)



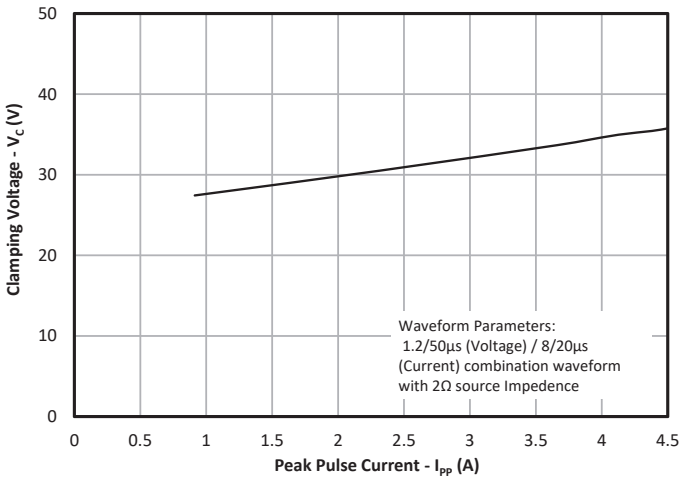
TLP Characteristic (Negative Pulse)



Capacitance vs. Reverse Voltage



Clamping Voltage Waveform (tp=1.2/50µs)



Typical Characteristics

Assembly Guidelines

The small size of this device means that care must be taken during the mounting process to ensure reliable solder joints. The figure at the right details Semtech's recommended mounting pattern. Recommended assembly guidelines are shown in Table 1. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing parameters will require some experimentation to get the desired solder application.

Solder Stencil

Stencil design is one of the key factors which will determine the volume of solder paste which is deposited onto the land pad. The area ratio of the stencil aperture will determine how well the stencil will print. The area ratio takes into account the aperture shape, aperture size, and stencil thickness. A minimum area ratio of 0.66 is preferred for the subject package. The area ratio of a rectangular aperture is given as:

Area Ratio = (L * W)/ (2 * (L + W) * T)

Where:
L = Aperture Length
W = Aperture Width
T = Stencil Thickness

Semtech recommends a stencil with square aperture and rounded corners for consistent solder release. The stencil should be laser cut with electro-polished finish. A stencil thickness of 0.075mm (0.003") is recommended. A 0.100mm (0.004") stencil may be used, however the stencil opening may need to be increased slightly to achieve the desired area ratio to ensure proper solder coverage on the pad.

Recommended Mounting Pattern

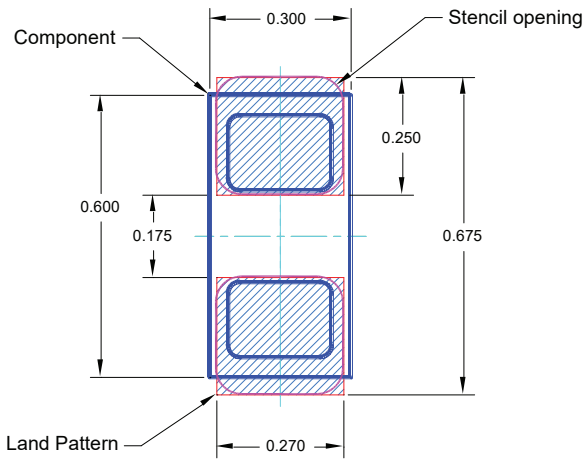
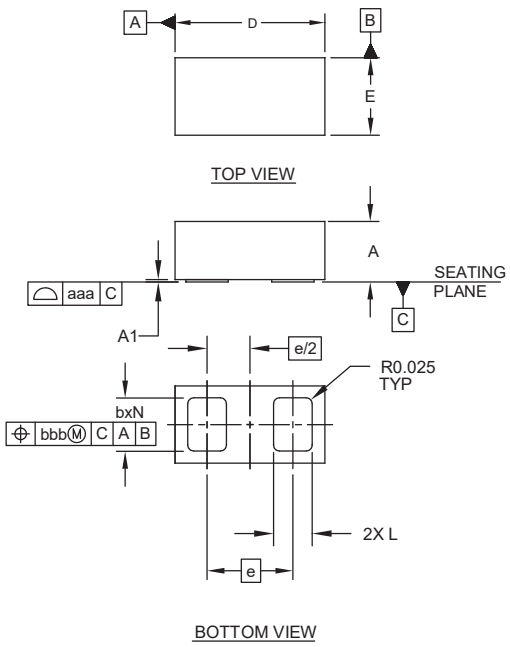


Table 1 - Assembly Guidelines

Assembly Parameter	Recommendation
Solder Stencil Design	Laser Cut, Electro-Polished
Aperture Shape	Rectangular with Rounded Corners
Solder Stencil Thickness	0.075mm (0.003") or 0.100mm (0.004")
Solder Paste Type	Type 4 Size Sphere or Smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Solder Mask Defined or Non Solder Mask Defined
PCB Pad Finish	OSP or NiAu

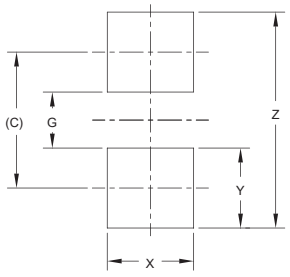
Outline Drawing - DFN 0.60 x 0.30 x 0.25mm-2 Lead



DIMENSIONS			
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.235	0.250	0.265
A1	0.000	0.010	0.050
b	0.200	0.220	0.240
D	0.580	0.600	0.620
E	0.280	0.300	0.320
e	0.355 BSC		
L	0.140	0.160	0.180
N	2		
aaa	0.08		
bbb	0.10		

NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

Land Pattern - DFN 0.60 x 0.30 x 0.25mm-2 Lead

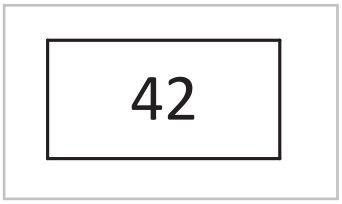


DIMENSIONS	
DIM	MILLIMETERS
(C)	(0.425)
G	0.175
X	0.270
Y	0.250
Z	0.675

NOTES:

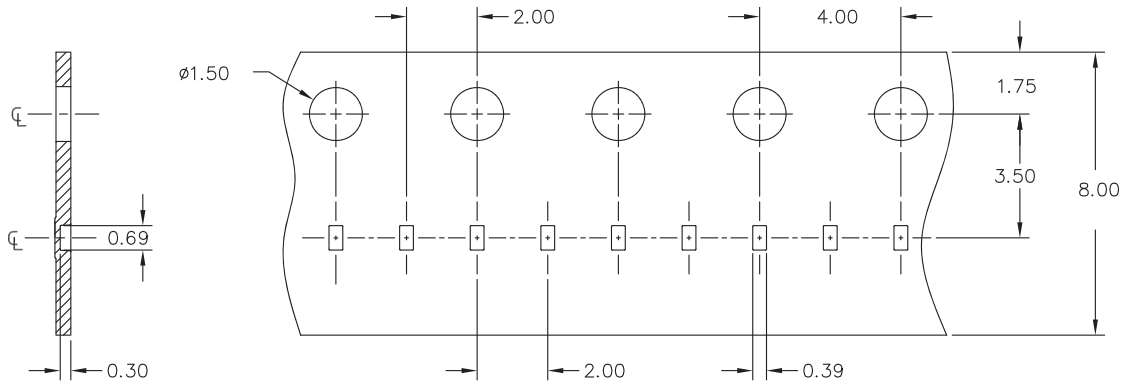
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
   CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
   COMPANY'S MANUFACTURING GUIDELINES ARE MET.

Marking Code

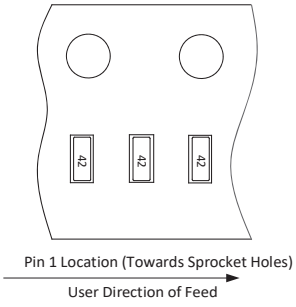


Note: Device is electrically symmetrical.

Tape and Reel Specification



Note: All dimensions are nominal dimensions in mm.



Order Information

PART NUMBER	QTY PER REEL	REEL SIZE
HClamp2481ZA.F	15,000	7"

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